

Douglas DeVoto

List of Publications by Year in descending order

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citing authors

#	ARTICLE	IF	CITATIONS
1	Bond Wire Damage Detection and SOH Estimation of a Dual-Pack IGBT Power Module Using Active Power Cycling and Reflectometry. IEEE Transactions on Power Electronics, 2020, 35, 6761-6772.	7.9	16
2	Parametric Design Study of a Power Electronics Package for Improving Solder Joint Reliability. , 2020, , .		1
3	Analysis and Optimization of a Multi-Layer Integrated Organic Substrate for High Current GaN HEMT-Based Power Module. , 2020, , .		12
4	A Comprehensive Review Toward the State-of-the-Art in Failure and Lifetime Predictions of Power Electronic Devices. IEEE Transactions on Power Electronics, 2019, 34, 4729-4746.	7.9	117
5	Bond Wire Damage Detection and State of Health Estimation of a 1200V, 900A Dual Pack IGBT Power Module using the RL-Equivalent Circuit. , 2019, , .		6
6	Liquid-Cooled Aluminum Silicon Carbide Heat Sinks for Reliable Power Electronics Packages. Journal of Electronic Packaging, Transactions of the ASME, 2019, 141, .	1.8	9
7	Degradation Modeling and Reliability Assessment of Capacitors. , 2019, , .		3
8	Thermal Assessment and In-Situ Monitoring of Insulated Gate Bipolar Transistors in Power Electronic Modules. , 2019, , .		1
9	Mechanical Characterization Study of Sintered Silver Pastes Bonded in a Double-Lap Configuration. , 2018, , .		2
10	A Review of Degradation Behavior and Modeling of Capacitors. , 2018, , .		41
11	Transient Liquid Phase Bonding of AlN to AlSiC for Durable Power Electronic Packages. Advanced Engineering Materials, 2018, 20, 1800039.	3.5	16
12	Reliability of Bonded Interfaces for Automotive Power Electronics. , 2013, , .		9
13	Thermal Performance and Reliability of Large-Area Bonded Interfaces in Power Electronics Packages. , 2011, , .		0